

Oscillator Technology in Focus

rakon

Enabling the
Connected Future

The logo for ITSF 2019 is a diamond shape formed by four thick, parallel lines in blue, red, and green. The text "ITSF 2019" is centered within the diamond.

ITSF
2019

Contents



- ◀ **Focus on the local oscillator requirements and advances for the radio head or remote radio unit(RRU)**
- ◀ **Discuss**
 - ◻ Advances in high stability TCXOs
 - ◻ The evolution of mini OCXOs
- ◀ **A short synopsis of Silicon and Quartz technology**
- ◀ **Consider the particular requirements of phase tolerance in the RRU and how this can be addressed**

RRU Frequency, Time and Phase

< Drivers for Frequency stability

- ❑ Radio head air interface tolerance (50ppb → measured in 1ms)
- ❑ If holdover is required, then dominated by the requirements for time synchronisation
 - To hold time to the sub micro second region over periods of many seconds
 - 1us over 100 seconds >> frequency accuracy of <10ppb

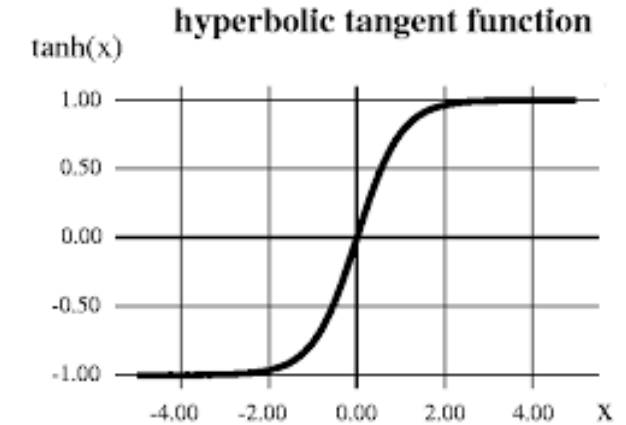
< Drivers for Time stability (65ns/130ns/260ns in front-haul)

- ❑ At start-up, needs to be conditioned, has to have access to time reference
- ❑ Conditioning bandwidth dependent on PTP signal quality and availability of physical layer synchronisation
- ❑ Low loop bandwidth implies short-to-medium term environmental stability of oscillator
 - Determines the local oscillator frequency stability, lower slope (frequency change with time)

< Drivers for Phase stability (sub-picosecond)

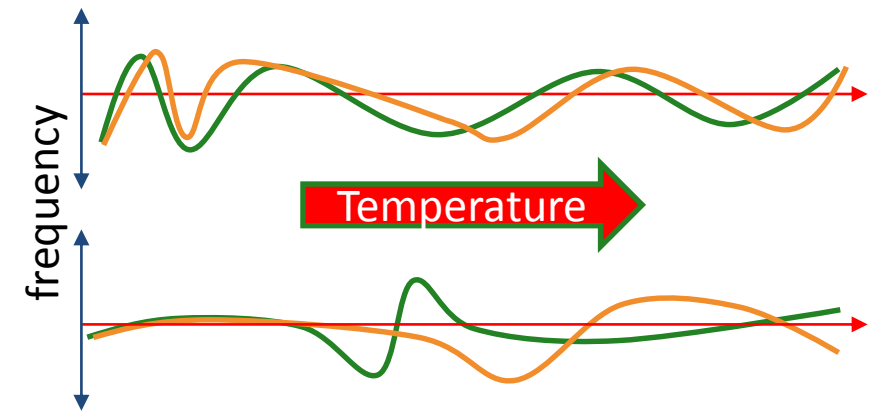
- ❑ Complex modulation schemes and higher carrier frequencies
- ❑ Directional antenna, beam forming

Higher Stability TCXOs



Traditional High stability TCXO

- ❑ What are the challenges?
- ❑ How are they addressed in a “post-compensated TCXO”?
 - Take a high stability standard VC-TCXO and add extra isolation
 - Add extra compensation (either Digital or Analogue) to reduce:
 - Higher order residual error generated by original non-ideal compensation scheme
 - Largely predictable, 6th order comp. implies 7th order error.
 - Piecewise Linear combination
 - Perturbations in frequency temperature curve of crystal
 - Unpredictable and more variable
 - Multiple Tanh(x) segments, give flexibility
 - Digital compensation requires high resolution digital temperature sensor and high resolution D/A, to reduce digitation effects.



The challenges, Standard TCXO device construction



< Traditional construction:

- Driven by cost and size requirements rather than performance (mobile devices, phones, location)
 - This has led to: 1 Resonator, 1 ASIC (including a built in temperature sensor) and 1 or 2 Ceramic Packages
- NB resonator and temperature sensor do not have strong thermal coupling



7x5



5x3.2



Double Decker



Double Decker, inverted



Integrated



H package

Thermal coupling

Post compensation TCXO devices - Isolation

Isolation - thermal

- Supply and load variations: cause the power dissipation in the ASIC to change and hence induce a small temperature offset in the sensor relative to the resonator, distorting the frequency vs temperature.
- Mounting: during calibration TCXO held in a jig, whereas in use it is soldered down on a pcb.

Isolation - electrical

- Single package - difficult to shield output stage from oscillator connections

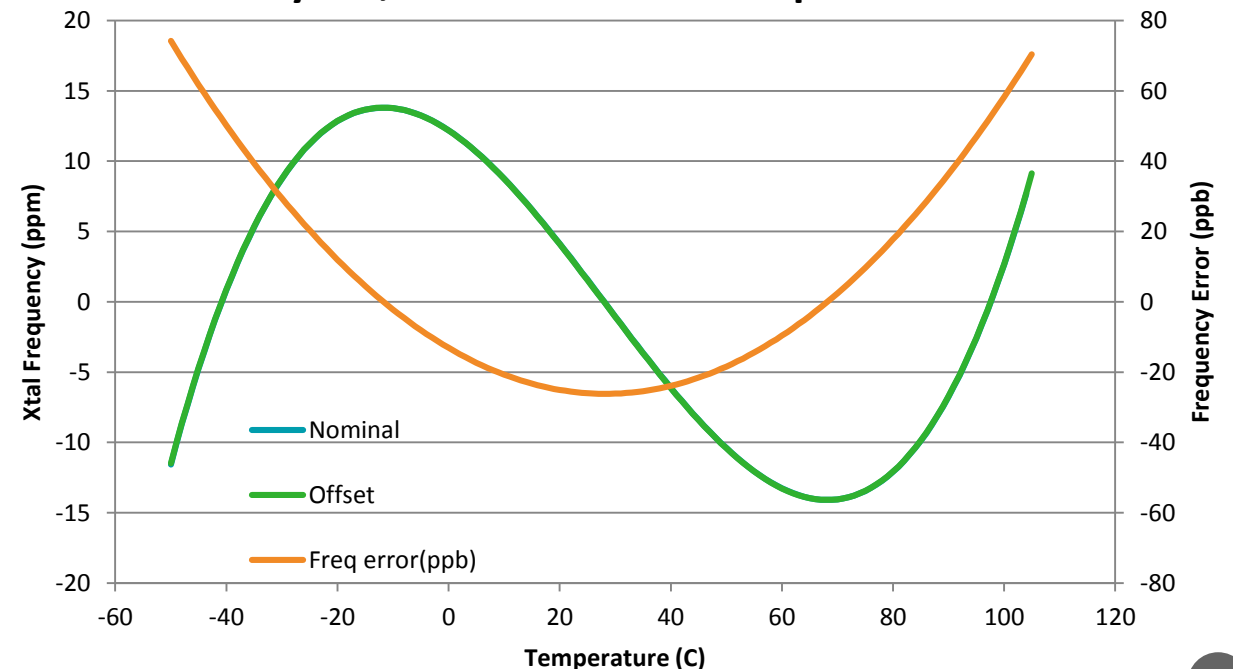
Both these contributions to instability increase markedly with frequency

- Higher power consumption, hence larger power variation
- Higher frequency, hence more feedback

Thermal degradation effect – Sensor to resonator differential

- Assuming say 10% supply on 6mA at 3.3V(20mW), ~2mW and thermal resistance of 25C/W then implies 0.05C variation. Gives ~ **50ppb** degradation.

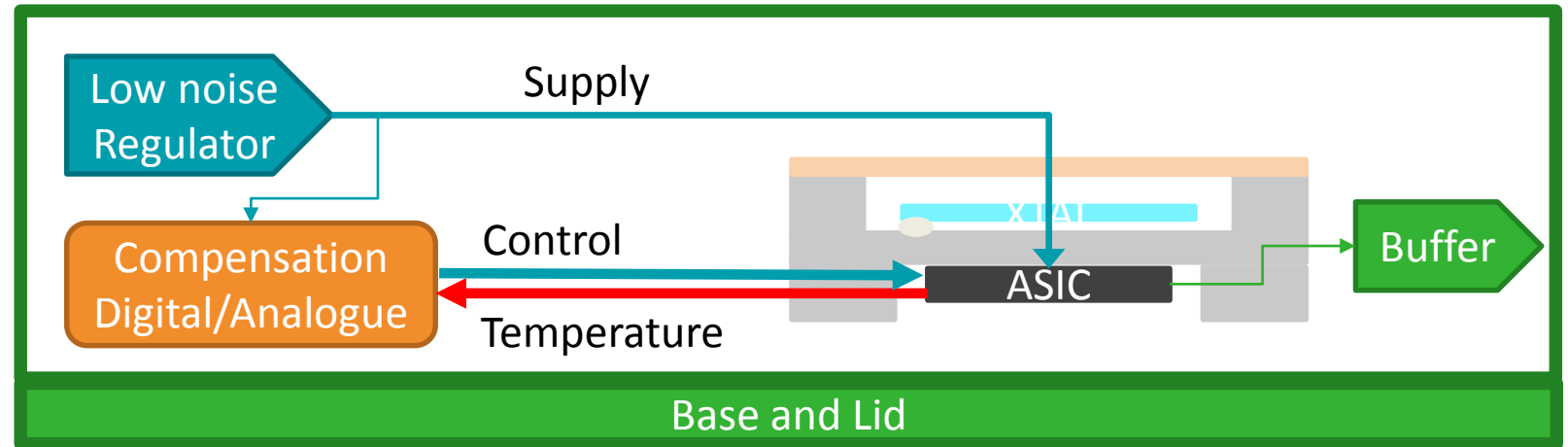
AT-cut crystal, effect of 0.05C temperature offset



Post compensation TCXO

< Elements:

- ❑ VC-TCXO
- ❑ Temperature Sensor
- ❑ Compensation
- ❑ Regulator
- ❑ Buffer
- ❑ Lid & Base

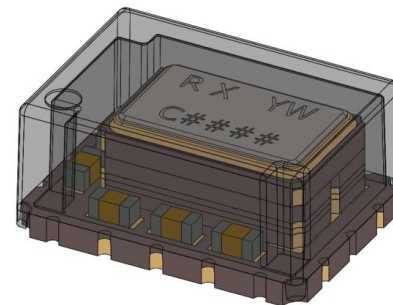


< Available sizes, Discrete construction

- ❑ 14x9, 9x7

< With Integration

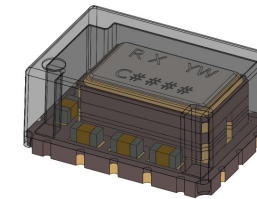
- ❑ Regulator, buffer and compensation together
- ❑ 7x5 using 5x3.2 VCTCXO
- ❑ 5x3.2 using 3.2x2.5 VCTCXO



Higher stability TCXO

< Post compensation and isolation enables

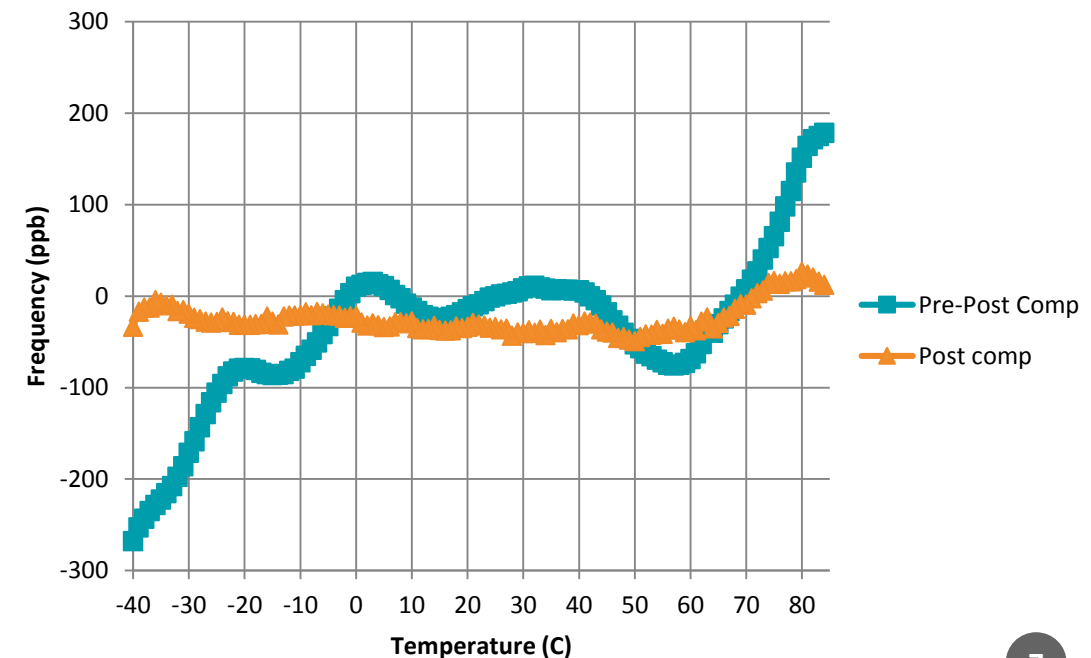
- Higher stability, (150ppb → < 30ppb)
 - Allows for wider temperature range -40 to 95 or 105C
- Lower frequency vs temperature slope, (20ppb/C → < 5ppb/C)
 - Allows better sync tolerance, lower MTIE over longer loop times
- Very low frequency change vs supply and load
 - 1 to 2 ppb, for 5% supply and 5pF load change
- High PSRR, no requirement for low noise supply
- Better airflow tolerance, reflow/mounting tolerance



< Higher frequency oscillators with good stability

- Lower jitter whilst maintaining stability

Post compensation example



Mini OCXO - Evolution

< Crystals - mini OCXOs use strip crystals rather than traditional round blanks

- AT-cut strip (2010) → SC-cut strip(2016)

< SC-cut strip, evolution

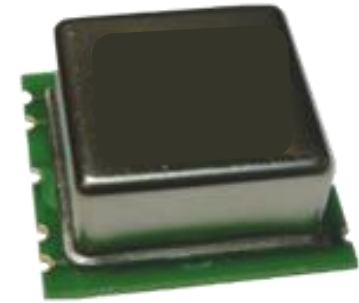
- 5x3.2 strip crystal → 3.2x2.5 strip crystal
 - Higher frequency, smaller package
- Fundamental → Third overtone
 - Higher frequency, lower aging

< Maturity and volume

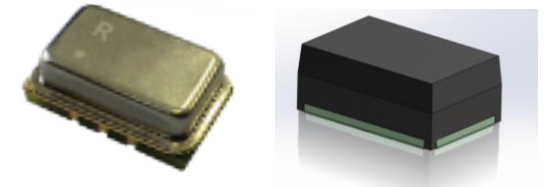
- Process improvements
 - Lower aging
 - Higher yield
- Design improvements
 - Lower g-sensitivity
 - Higher maximum temperature
 - 85 → 95C → 105C
- Lower cost

< New ASIC generations

25x22x12



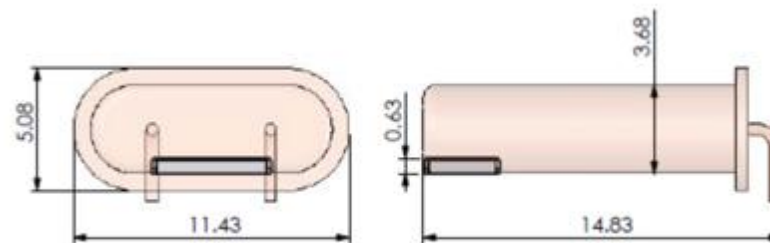
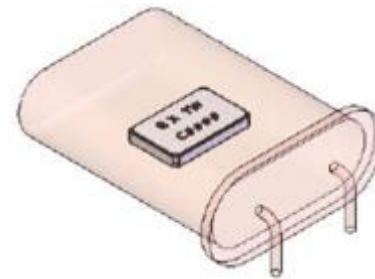
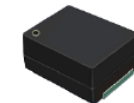
14x9x6



9x7x4

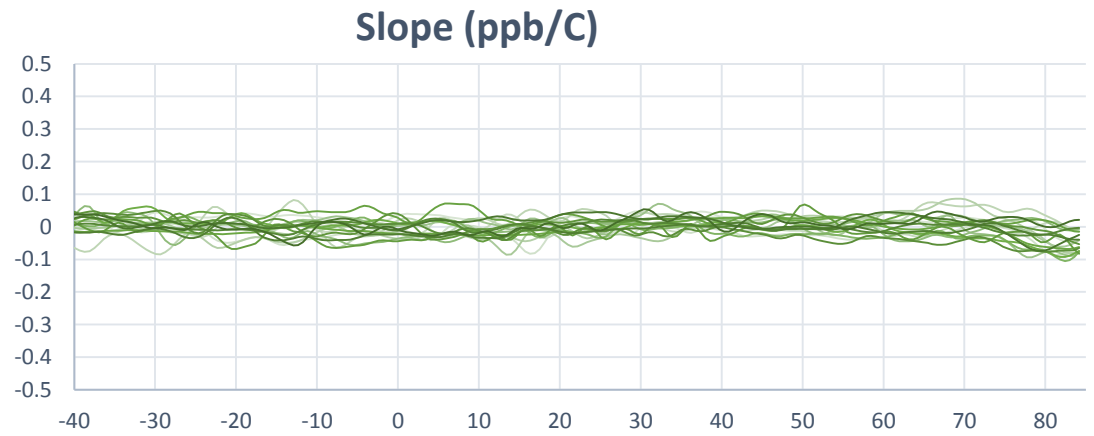
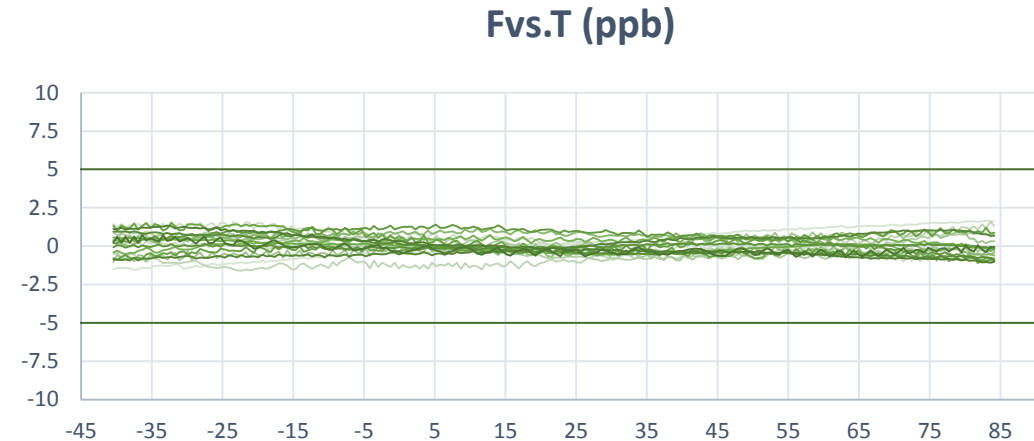
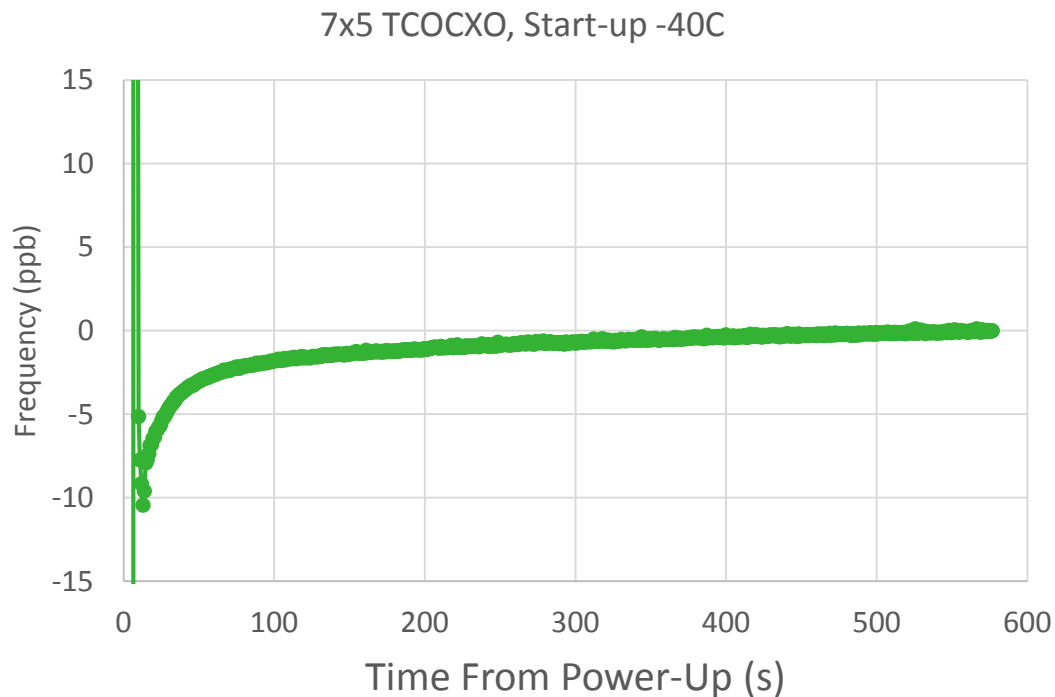


7x5x3



Fast start-up, with maintained stability

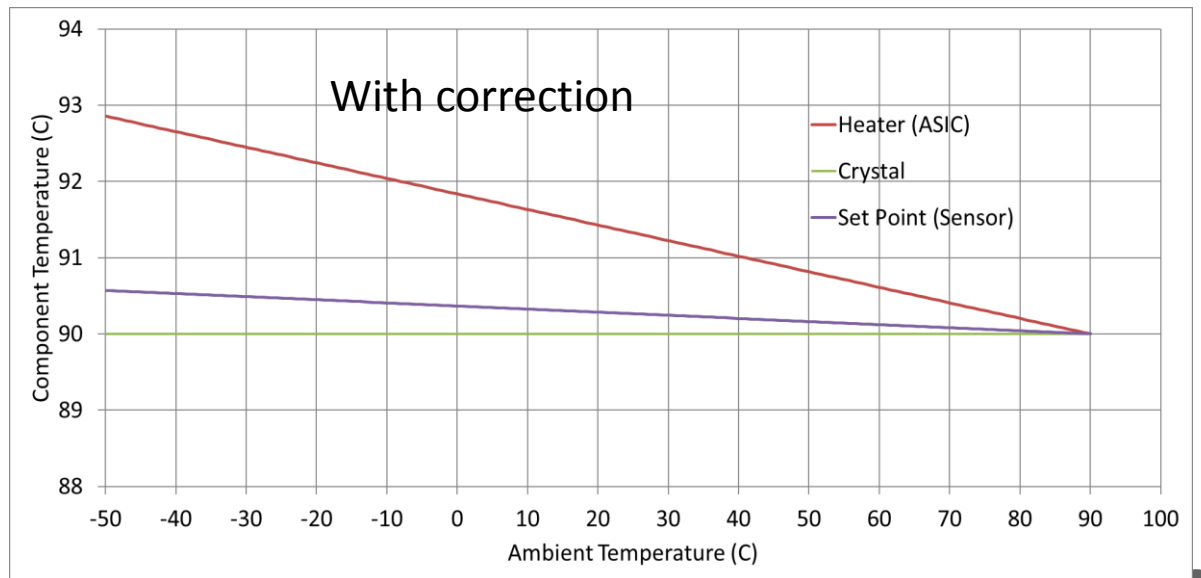
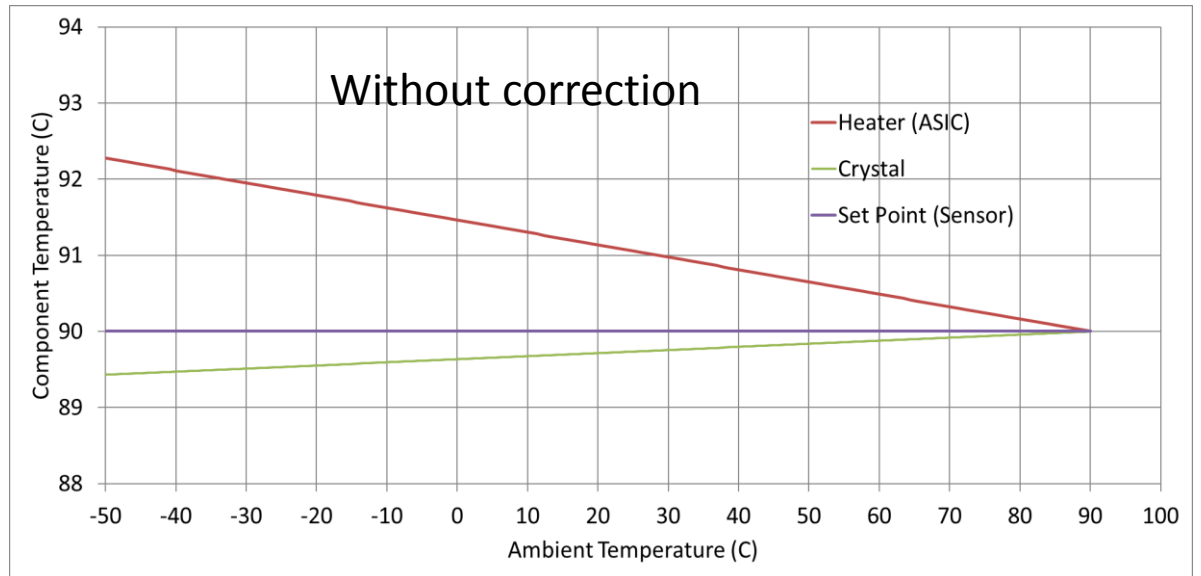
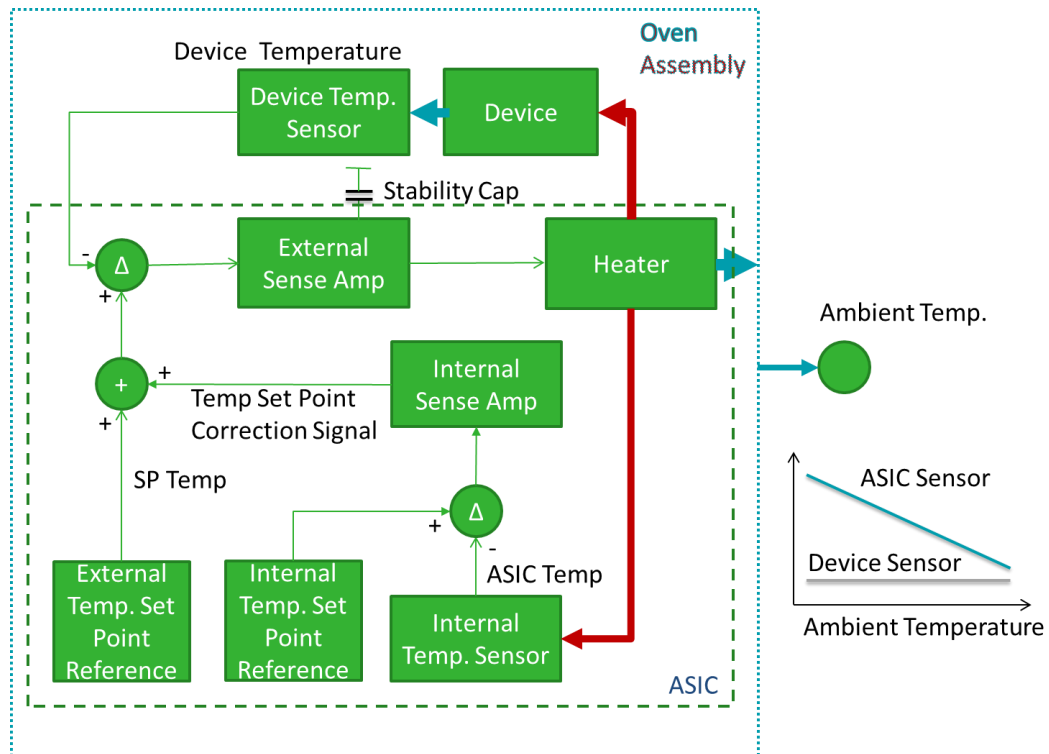
- Radio head traditionally had fast start-up VCXO
- Mini integrated OCXO (7x5)
 - Within 10ppb in ~10 seconds @ -40C
 - Compared to 2 to 3 minutes for 25x22 OCXO



Mini OCXO evolution: Set Point Error Correction

Set point error correction

- ❑ Senses ambient temperature and apply correction to the residual frequency error
- ❑ Corrects the cause of the main frequency error
- ❑ Takes stability down from 5ppb to < 1ppb



Mini OCXO Jitter Evolution

Improvements in ASIC technology

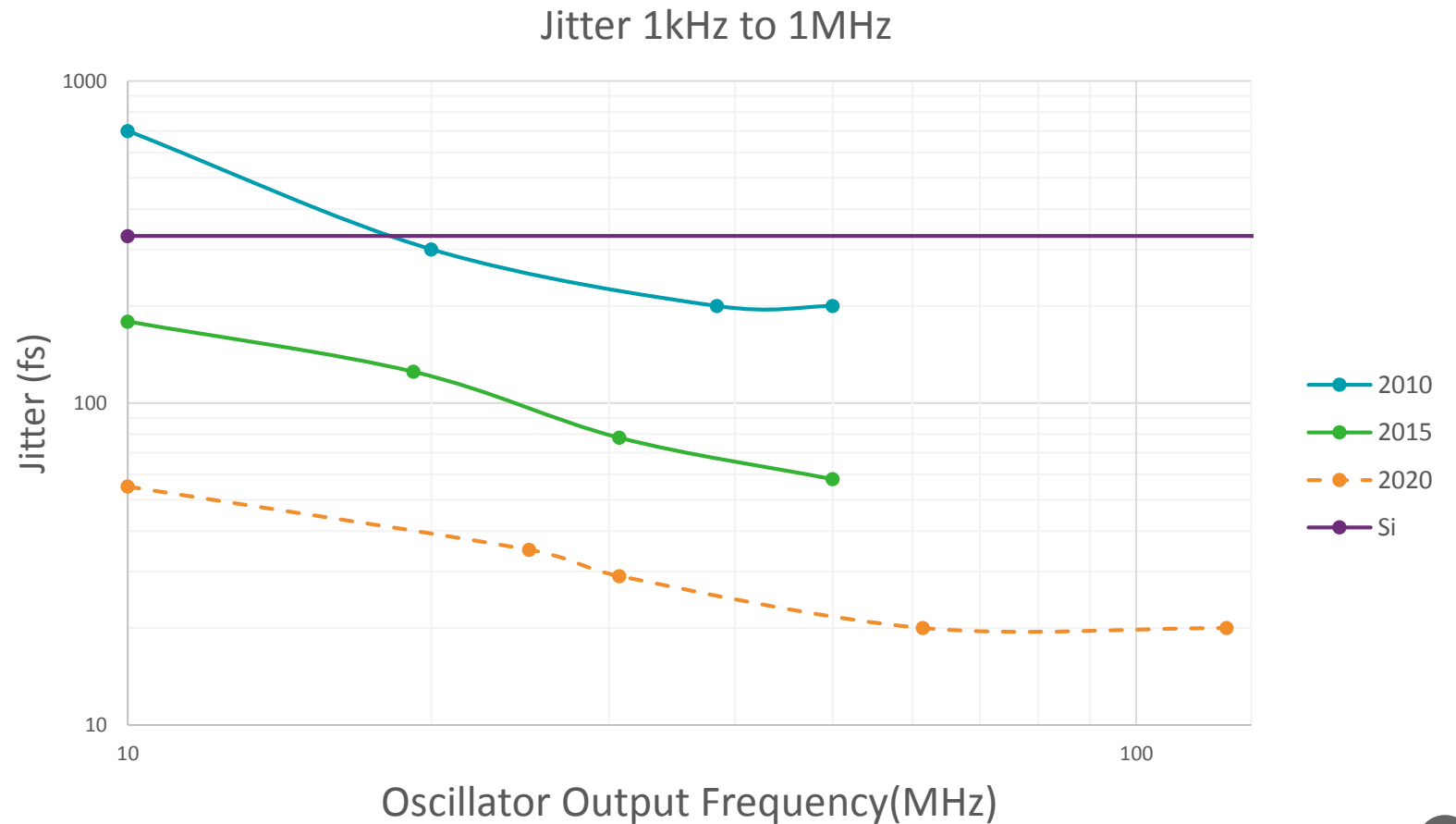
- ❑ Faster, lower noise processes
- ❑ Oscillator and Output Buffer Phase noise floor improvement
 - $-150 \rightarrow -160 \rightarrow -170$ dBc/Hz

Higher frequency resonators

- ❑ Higher frequency SC-cut
- ❑ Third overtone strip crystals

Phase Jitter

- ❑ Jitter floor (1kHz to 1MHz)
 - $200\text{fs} \rightarrow 60\text{fs} \rightarrow 20\text{fs}$



Silicon vs Quartz

< Silicon

- ❑ Not piezoelectric
- ❑ Resonator electrostatic coupling
- ❑ Lack of fine frequency adjustment
- ❑ Lack of direct oscillator adjustment

< TCXO/OCXO achieved by:

- ❑ Fixed frequency silicon MEMs oscillator
- ❑ High resolution frequency adjustment via Frac-N PLL synthesiser

< Temperature sensor

- ❑ Two resonators, one low temperature coefficient, one high temperature coefficient. Thermally coupled.
- ❑ Difference frequency gives high resolution digital temperature measurement

< Temperature Compensated Synthesiser(TCS)

- ❑ Stability is constant with output frequency
- ❑ Jitter is constant with output frequency
 - Jitter relatively high, in the effective bandwidth

< Quartz

- ❑ Piezoelectric, simple coupling
- ❑ Large Resonator frequency range
 - 32kHz tuning fork to 2GHz SAW
 - Standard BAW resonators span ~1 to~ 600MHz
- ❑ Higher Q resonator, even with higher coupling
- ❑ Resonator has individual fine frequency adjustment in manufacture
- ❑ Oscillator Adjustable in circuit (VCXO)

< Stability very good, but traditionally gets worse as frequency increases

< Jitter relatively low and improves significantly as frequency increases

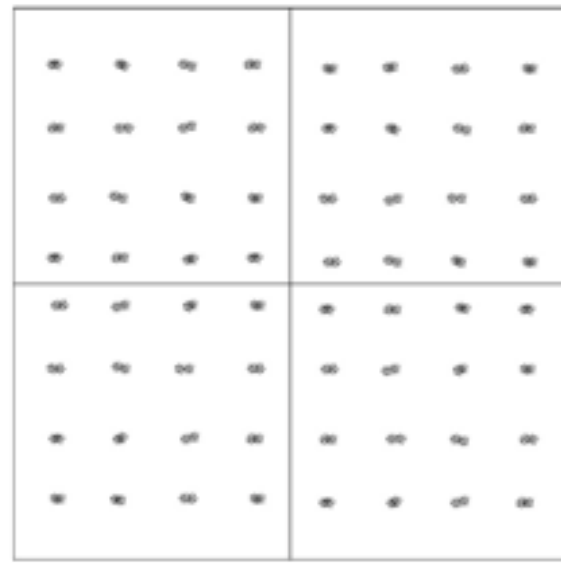
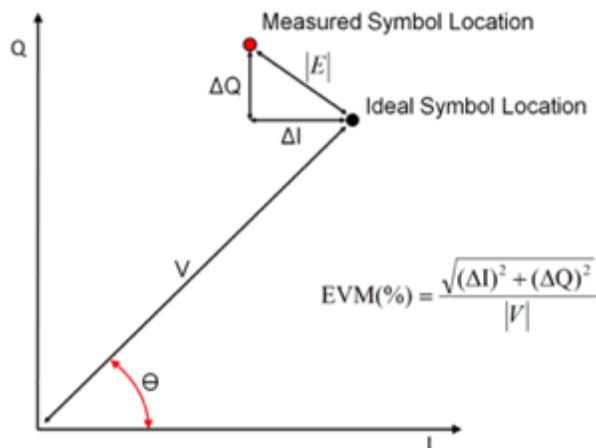
RRU Phase Jitter requirements

< Drivers for phase stability, low jitter, EVM (Error Vector Magnitude)

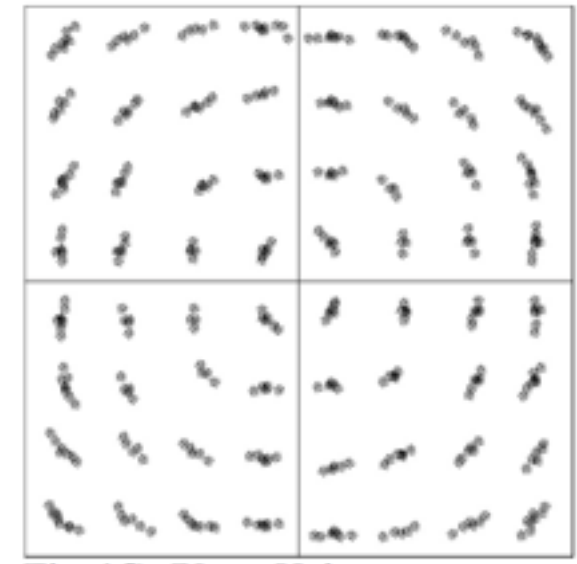
- Higher QAM values 16,64,256 and Higher carrier frequency (<1GHz →3-4GHz→24-28GHz)

< Imposes Requirements on the oscillator/pll multiplication chain

- Requirements for phase/time stability of <~100fs region over times of <~ 100us
- Oscillator chain, frequency multiplied up to the carrier/modulation rate.
- Integral of phase spectral density over a bandwidth



QAM 64 Ideal Constellations



Constellations with high phase noise

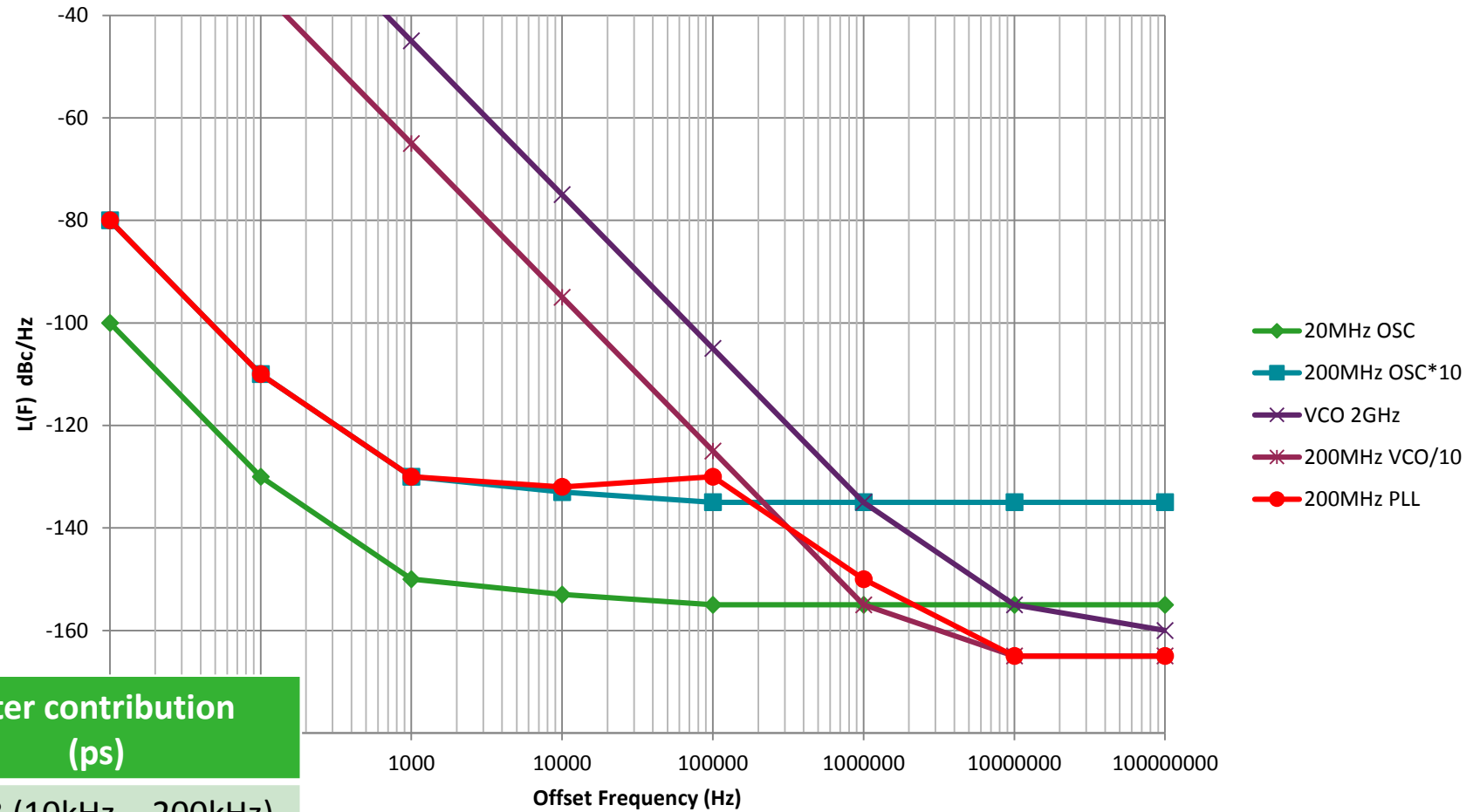
Oscillator/PLL chain - multiplying the frequency up

- < Idealised example
- < Locking high frequency VCO to low frequency crystal oscillator

□ Example 200MHz output from 20MHz TCXO and 2GHz VCO

- TCXO 20MHz
- TCXO * 10
- VCO 2 GHz
- VCO /10
- 200MHz PLL output

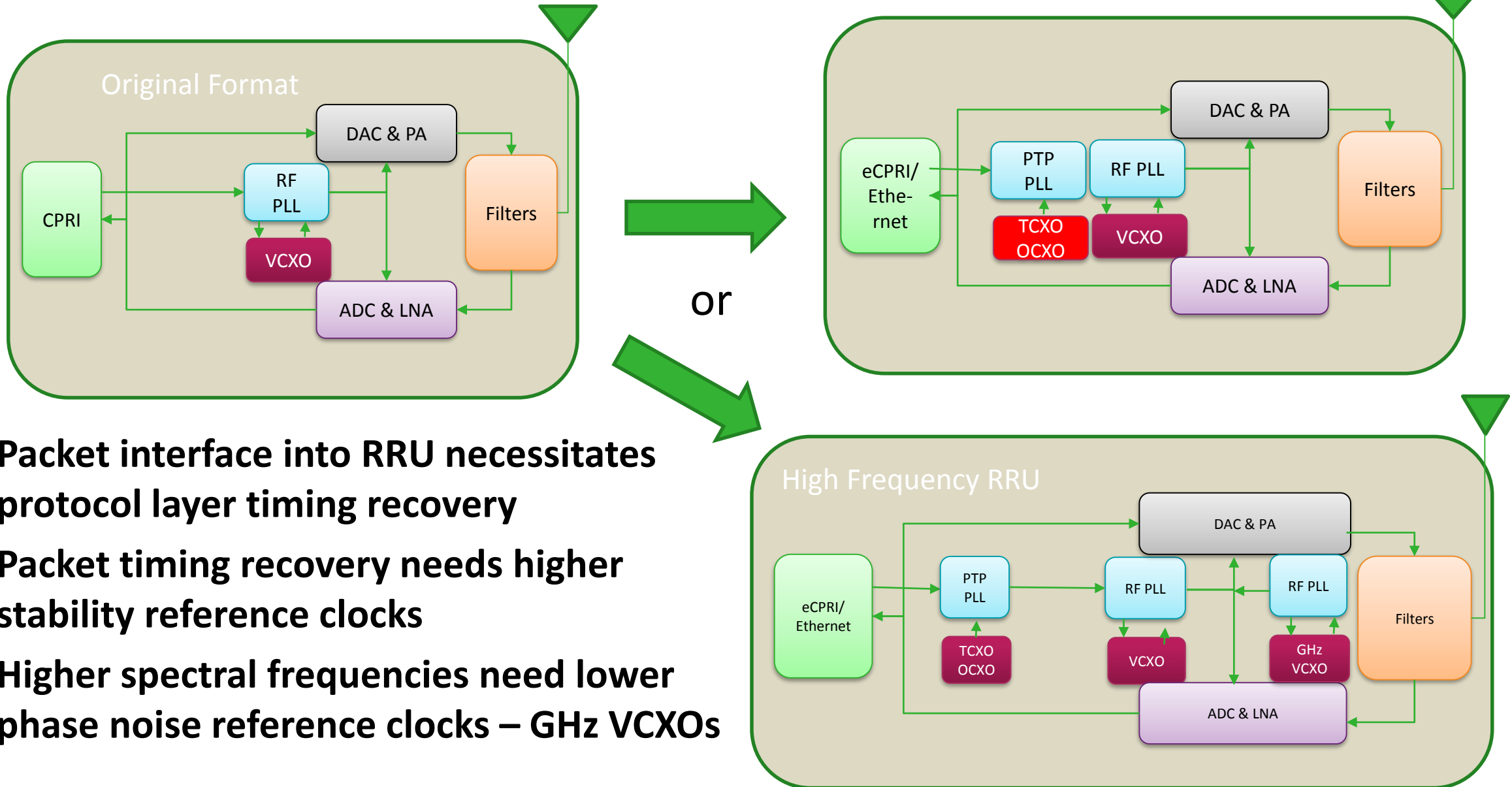
PLL Phase Noise



← Jitter bandwidth →

Oscillator	Jitter 10kHz- 20MHz (ps)	Jitter contribution (ps)
TCXO	0.89	~0.08 (10kHz – 200kHz)
VCO	1.41	~0.08 (200kHz – 20MHz)
PLL	0.17	~0.17(10kHz – 20MHz)

5G Remote Radio Unit. Timing evolution



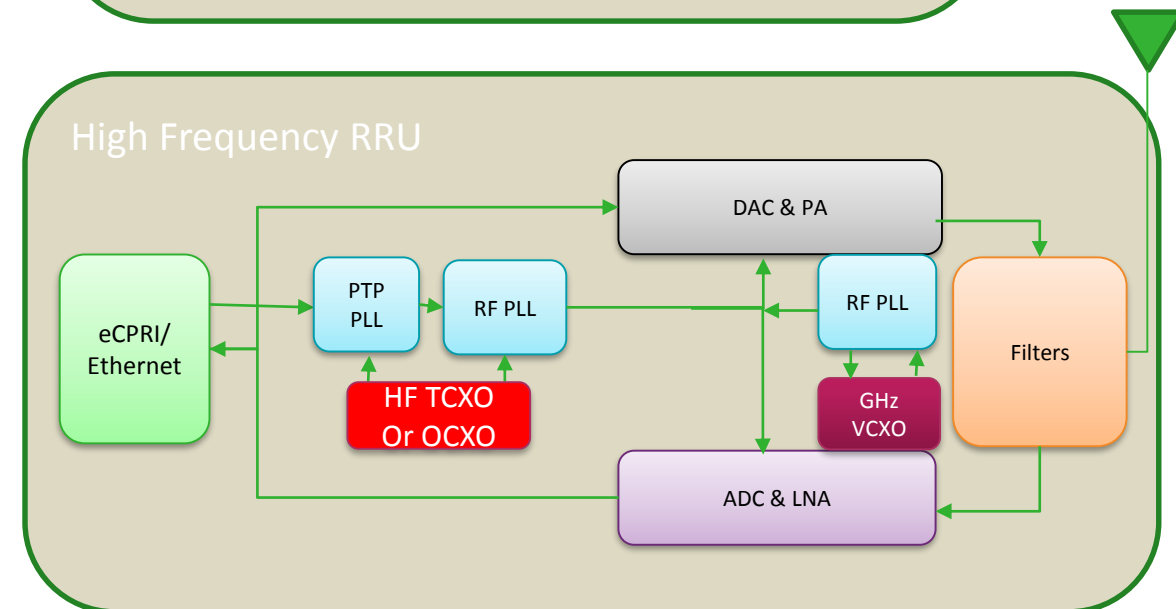
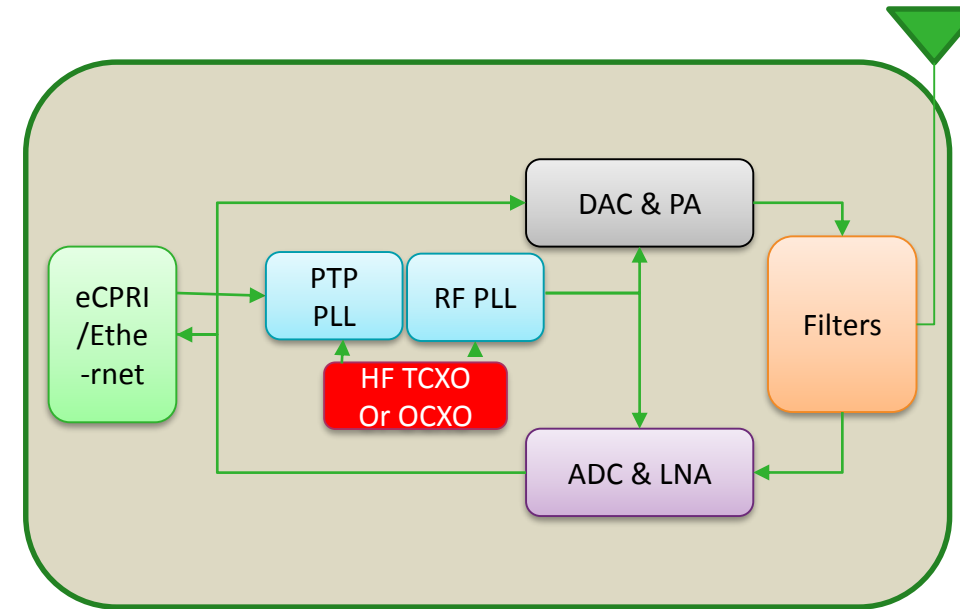
- Packet interface into RRU necessitates protocol layer timing recovery
- Packet timing recovery needs higher stability reference clocks
- Higher spectral frequencies need lower phase noise reference clocks – GHz VCXOs

Multiplying the frequency up

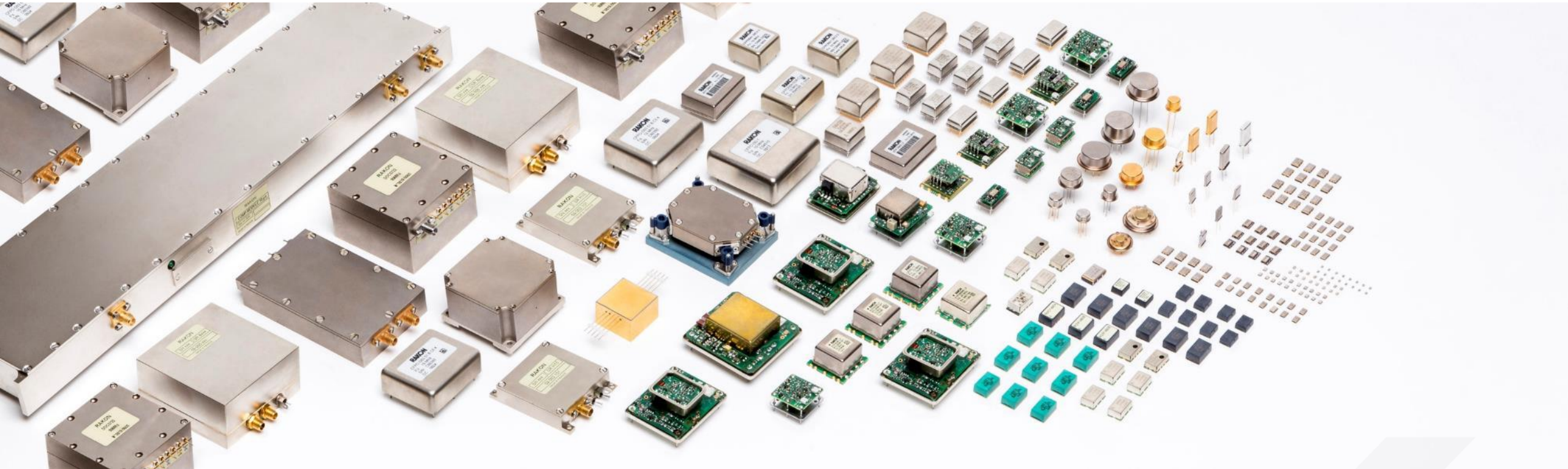
- ◀ **Jitter stays the same with idealised frequency multiplication/division**
- ◀ **Lower frequency oscillator only contributes up to PLL loop bandwidth**
 - Jitter should be specified for appropriate bandwidth, probably around 1kHz to 1MHz
 - Higher Q VCO, allows lower loop bandwidth, reduces jitter of composite PLL output
- ◀ **May have multiple loops, jitter attenuators**
 - GHz VCO, locked to high frequency VCXO/XO, locked to low frequency TCXO/OCXO
 - High GHz VCO, locked to GHz VCXO/XO, locked to high frequency VCXO/XO, locked to TCXO/OCXO
- ◀ **Can save costs if simplified, remove high frequency VCXO/XO and go directly from TCXO/OCXO to GHz VCO**
 - Requires: Very Low jitter, high stability reference oscillator together with very good VCO/PLL

The future RRU oscillator?

- < **Lower jitter higher stability TCXO and OCXO options available now and set to improve substantially**
- < **Can combine both the low jitter and high stability into one oscillator**
 - High frequency low jitter TCXO or OCXO
- < **Exact requirements for time and frequency sync. performance of local oscillator, still evolving:**
 - Heavily dependent on known quality of interface to RRU. Input specification.
 - Future output constraints, tighter time and phase tolerances.



Oscillator Technology in Focus.



Dr Nigel Hardy